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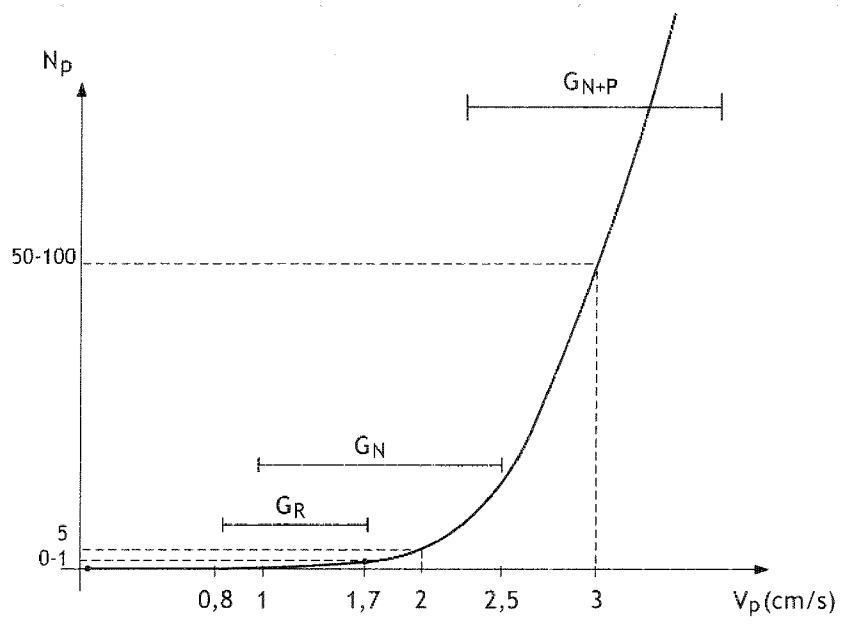
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(54) Title: PROCESS AND EQUIPMENT FOR BONDING BY MOLECULAR ADHESION



(57) Abstract: The invention relates in a first aspect to a process for bonding by molecular adhesion of two substrates to one another during which the surfaces of said substrates are placed in close contact and bonding occurs by propagation of a bonding front between said substrates, characterised in that it comprises prior to bonding a step consisting of modifying the surface state of one and/or the other of said substrates so as to regulate the propagation speed of the bonding front. The surface state is modified by locally or uniformly heating the surface of one and/or the other of the substrates to be bonded, or again by roughing the surface of one and/or the other of the substrates.

WO 2007/060145 A1

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